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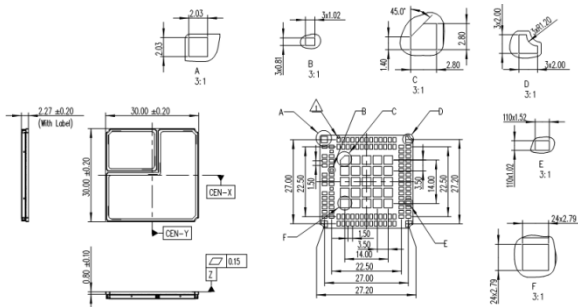
Thank you for purchasing HUAWEI MU709s-6 HSPA+ LGA Module (hereinafter referred to as the MU709)

Note:

- This manual briefly describes the preparation, the process for PCB Design, Assembly and safety precautions.
- You are recommended to read the manual before using the MU709.

Getting to Know the MU709

- The package of the LGA module is 145 pin LGA with a dimension of 30 mm × 30 mm × 2.27 mm. It is applied to the user interface board, and can be used as a wireless terminal in a network environment.



Requirements on PCB Layout

- To reduce deformation, a thickness of at least 1.0 mm is recommended.
- Other devices must be located more than 3 mm (5 mm recommended) away from the LGA module. The minimum distance between the LGA module and the PCB edge is 0.5 mm.
- When the PCB layout is double sided, it is recommended that the LGA module be placed on the second side for assembly; so as to avoid module dropped from PCB or component (located in module) re-melting defects caused by uneven weight.

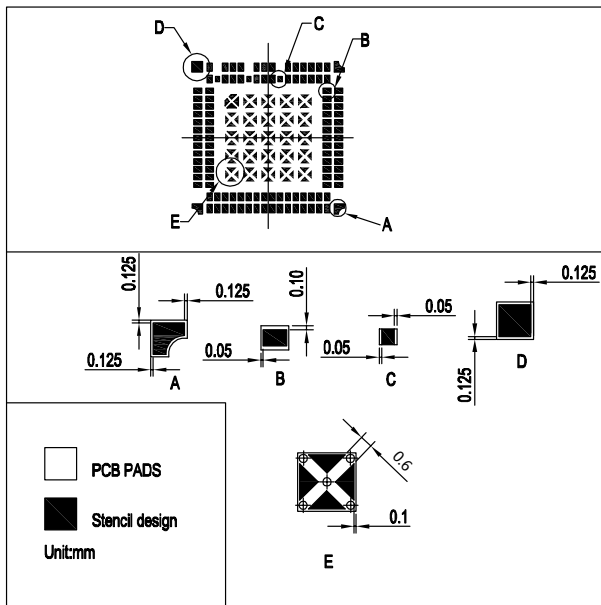
Design of Solder Mask

- The PCB pad design can be solder mask defined (SMD), or non-solder mask defined (NSMD). NSMD is recommended. In addition, the solder mask of the NSMD pad design is larger than the pad so the reliability of the solder joint can be improved.
- The solder mask must be 100 μm to 150 μm larger than the pad, that is, the single side of the solder mask must be 50 μm to 75 μm larger than the pad. The specific size depends on the processing capability of the PCB manufacturer.

Assembly

Stencil Design

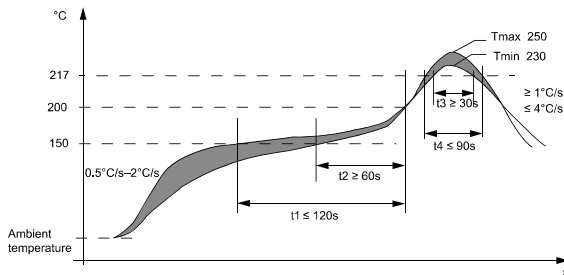
It is recommended that the stencil for the LGA module be 0.15 mm in thickness. For the stencil design, see the following figure:



Reflow Profile

For the soldering temperature of the LGA module, see the following figure.

Reflow profile



Reflow parameters

Temperature Zone	Time	Key Parameter
Preheat zone (40°C–150°C)	60s–120s	Heating rate: 0.5°C/s–2°C/s
Soak zone (150°C–200°C)	(t_1 – t_2): 60s–120s	Heating rate: < 1.0°C/s

Reflow zone ($> 217^{\circ}\text{C}$)	($t_3 - t_4$): 30s–90s	Peak reflow temperature: 230°C–250°C
Cooling zone	Cooling rate: $1^{\circ}\text{C/s} \leq \text{Slope} \leq 4^{\circ}\text{C/s}$	